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(57) **ABSTRACT**

An electronic apparatus including at least one heat generating component and an immersion cooling system is provided. The immersion cooling system includes a box body and a condensation module. The box body is adapted to accommodate a coolant, and the heat generating component is disposed in the box body to be immersed in the coolant in a liquid state. The condensation module includes a pipeline and a condensate, and the pipeline passes through the box body and is adapted for the condensate to flow. At least one parameter of the condensate may be changed to lower a boiling point of the coolant to a predetermined value by lowering the temperature in the box body with the condensate. In addition, an operating method of the electronic apparatus is also provided.

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